

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
M122-1384SERIAL NO.
09/602,395LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
John T. MooreFILING DATE
June 22, 2000GROUP
2812

U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TSP	AA	5,032,545	07/91	Doan et al.	437	242	10/1990
TSP	AB	5,436,481	07/95	Egawa et al.	257	324	1/1994
TSP	AC	5,378,645	01/95	Inoue et al.	437	47	5/1993
TSP	AD	5,258,333	11/93	Shappir et al.	437	235	8/1992
TSP	AE	5,518,946	05/96	Kuroda	437	52	2/1994
TSP	AF	5,445,999	08/95	Thakur et al.	437	241	11/1992
TSP	AG	5,382,533	01/95	Ahmad et al.	437	24	1/1995
TSP	AH	5,663,077	09/97	Adachi et al.	438	151	9/1994
TSP	AI	5,026,574	06/91	Economu et al.	427	248.1	1/1989
TSP	AJ	5,612,558	11/95	Harshfield 3.47	257	298	3/1997
TSP	AK	5,719,083	06/95	Komatsu 2.98	438	652	6/1995
TSP	AL	5,760,475	11/94	Cronin 6.98	257	758	11/1994

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
TSP	AM	WO 96/39713	12/96	PCT	—	—	✓	
	AN							
	AO							
	AP							
	AQ							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

TSP	AR		Wolf, S., "Silicon Processing for the VLSI Era", Lattice Press 1990, Vol. 2, pp. 212-213.
TSP	AS		Wolf, S., "Silicon Processing for the VLSI Era", Lattice Press 1990, Vol. 2, pp. 188-189, 194-195, 609-614.
TSP	AT		Ko, L. et al., "The Effect of Nitrogen Incorporation into the Gate Oxide by Using Shallow Implantation of Nitrogen and Drive-In Process", IEEE 1996, pp. 32-35.

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form PT-149

**U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE**

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U.S. PATENT DOCUMENTS


*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TSP	AA	5,834,372	12/95	Lee <i>11/98</i>	438	677	12/1995
TSP	AB	5,619,057	04/96	Komatsu <i>4/97</i>	257	382	4/1996
	AC	5,663,036	05/97	Seebauer et al.			
TSP	AD	6,054,396	04/00	Doan	438	763	8/1997
TSP	AE	6,174,821	01/01	Doan	438	763	6/1997
TSP	AF	5,939,750	08/99	Early	257	321	1/1998
TSP	AG	5,254,489	10/93	Nakata	437	40	10/1991
TSP	AH	5,464,792	11/95	Tseng et al.	437	160	1/1994
TSP	AI	5,620,908	04/97	Inoh et al.	438	207	7/1995
TSP	AJ	5,716,864	02/98	Abe	437	43	1/1996
TSP	AK	5,972,783	10/99	Arai et al.	438	513	2/1997
TSP	AL	6,093,661	07/00	Trivedi et al.	438	769	8/1999

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		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
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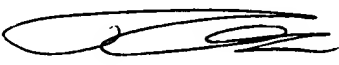
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

TSP	AR	Doyle, B. et al., "Simultaneous Growth of Different Thickness Gate Oxides in Silicon CMOS Processing", IEEE Vol. 16 (7), July 1995, pp. 301-302.
TSP	AS	Kuroi, T. et al., "The Effects of Nitrogen Implantation Into P+Poly-Silicon Gate on Gate Oxide Properties", 1994 Sympos. on VLSI Technology Digest of Technical Papers, IEEE 1994, pp. 107-108.
TSP	AT	Liu, C.T. et al., "Multiple Gate Oxide Thickness for 2GHz System-on-a-Chip Technologies", IEEE 1998, pp. 589-592.

EXAMINER 

DATE CONSIDERED 11/27/01

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Form PTO-159 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. M122-1384		SERIAL NO. 09/602,395				
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				GROUP 2812				
U.S. PATENT DOCUMENTS								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
TSP	AA	5,994,749	11/99	Oda	257	411	1/1998	
TSP	AB	5,674,788	10/97	Wristers et al.	437	239	6/1995	
TSP	AC	5,596,218	01/97	Soleimani et al.	257	369	10/1993	
TSP	AD	5,960,302	09/99	Ma et al.	438	585	12/1996	
	AE							
	AF							
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